

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>KUO-SHU TSENG</td> <td>01/02/2014</td> </tr> <tr> <td>CHIEN-HUA CHEN</td> <td>01/02/2014</td> </tr> <tr> <td>YOU-FENG CHEN</td> <td>01/02/2014</td> </tr> <tr> <td>YEN-YU CHEN</td> <td>01/02/2014</td> </tr> <tr> <td>ZHONG-YI CHEN</td> <td>01/02/2014</td> </tr> <tr> <td>YUNG-HAW LIAW</td> <td>01/02/2014</td> </tr> </tbody> </table>		Name	Execution Date	KUO-SHU TSENG	01/02/2014	CHIEN-HUA CHEN	01/02/2014	YOU-FENG CHEN	01/02/2014	YEN-YU CHEN	01/02/2014	ZHONG-YI CHEN	01/02/2014	YUNG-HAW LIAW	01/02/2014
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YUNG-HAW LIAW	01/02/2014														
RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD														
Street Address:	NO.8, LI-HSIN ROAD. 6, SCIENCE-BASED INDUSTRIAL PARK														
City:	HSIN-CHU														
State/Country:	TAIWAN														
Postal Code:	300-77														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14146996</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14146996										
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Application Number:	14146996														
CORRESPONDENCE DATA															
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Correspondent Name:	MCCLURE, QUALEY & RODACK, LLP														
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NAME OF SUBMITTER:	DANIEL R. MCCLURE
Signature:	/Daniel R. McClure/
Date:	01/27/2014
Total Attachments: 2 source=00127460#page1.tif source=00127460#page2.tif	

(專利)

ASSIGNMENT

WHEREAS, Kuo-Shu TSENG, Chien-Hua CHEN, You-Feng CHEN, Yen-Yu CHEN, Zhong-Yi CHEN, and Yung-Haw LIAW

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD FOR CONTROLLING EXHAUST FLOW IN WAFER PROCESSING MODULE

Filed: 2014-01-03 Serial No. 14/146,996

Executed on: _____

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No.8, Li-Hsin Road, 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEES, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2014.01.02
 Date Name: Kuo-Shu TSENG (Last name: TSENG)

2014.01.02
 Date Name: Chien-Hua CHEN (Last name: CHEN)

2014.01.02
 Date Name: You-Feng CHEN (Last name: CHEN)

2014.01.02
 Date Name: Yen-Yu CHEN (Last name: CHEN)

2014.01.02
 Date Name: Zhong-Yi CHEN (Last name: CHEN)

1/2 2014
 Date Name: Yung-Haw LIAW (Last name: LIAW)